

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top	CF-003	0.018mm		
2	PP-top	PP-008	0.350mm	4.1	
2	Signal-1		0.035mm		
	Dielectric4	FR-4	0.320mm	4.8	
3	Signal-2		0.035mm		
	Dielectric5	FR-4	0.320mm	4.8	
4	GND-1	CF-004	0.035mm		
	Core	Core-039	0.730mm	4.5	
5	GND-2	CF-004	0.035mm		
	PP-bottom	PP-008	0.350mm	4.1	
6	Bottom	CF-003	0.018mm		
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	
	Board Layer Stack Bottom Overlay				

Total board thickness: 2.296mm

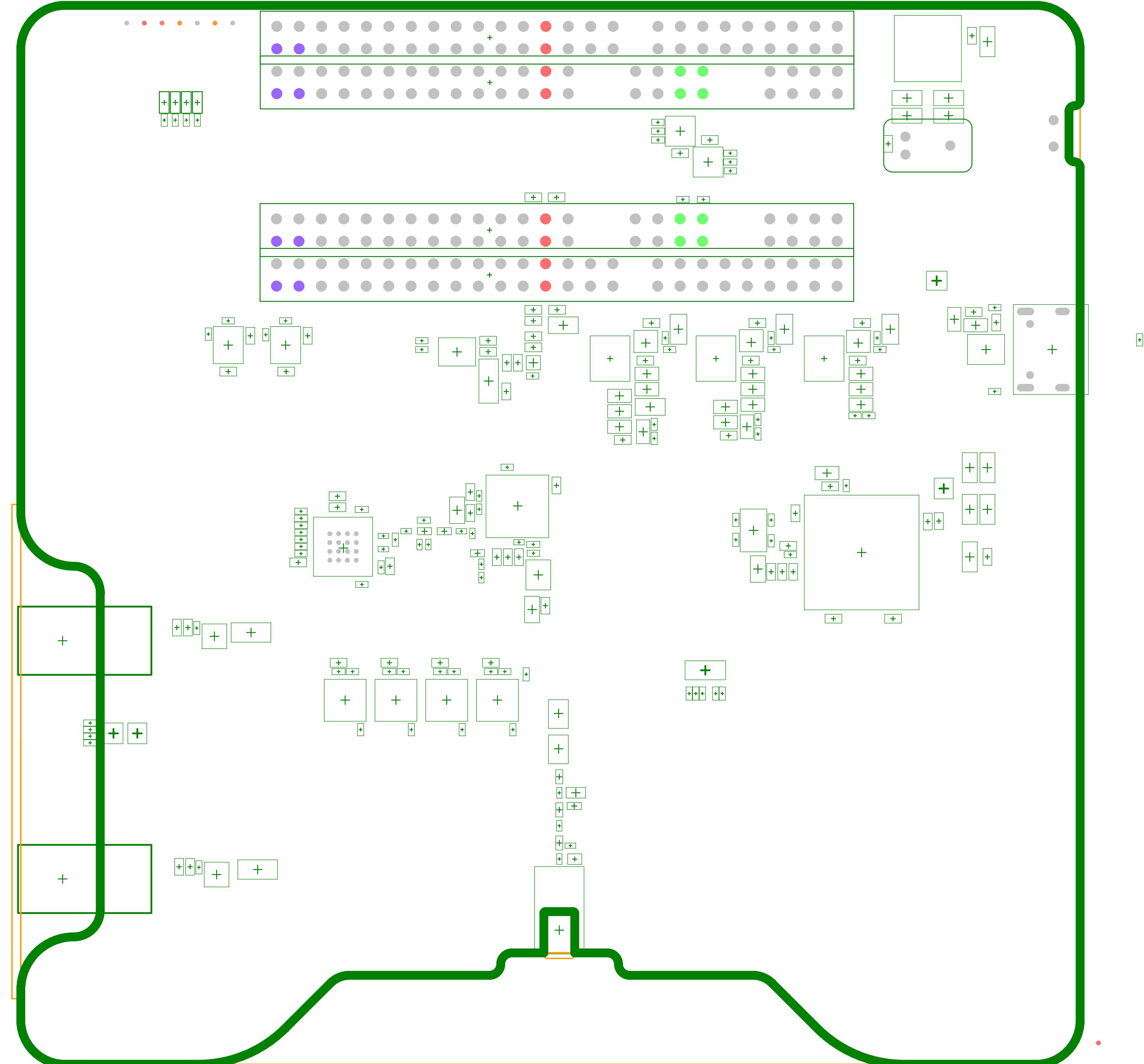
Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Board Shape Component Guard Dimension	
Component Guard	
Engineer: Juan Del Pino Mena	
Date: 2024-08-11	Revision: 0.3
	Size: A4

A

B

C

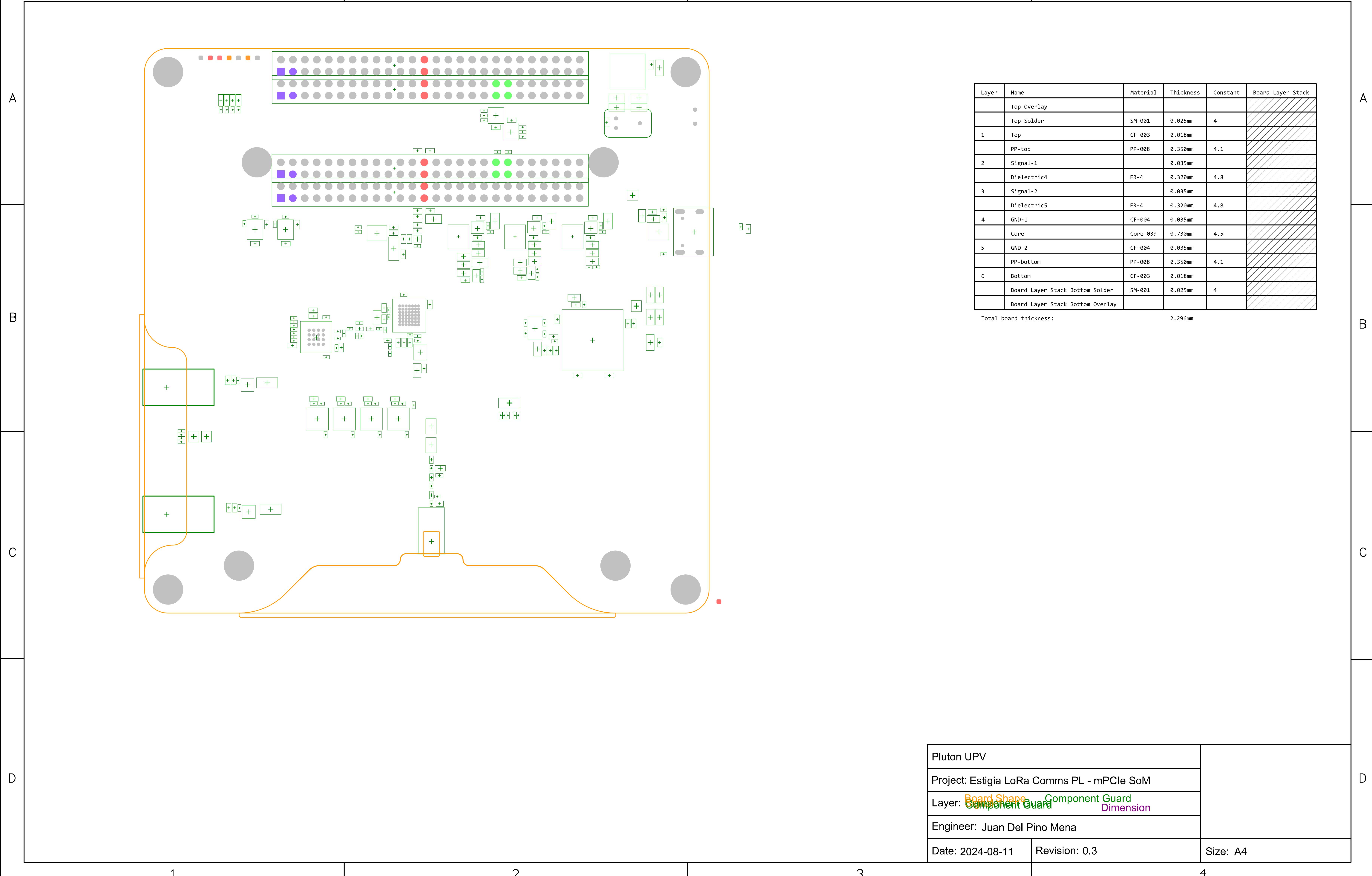
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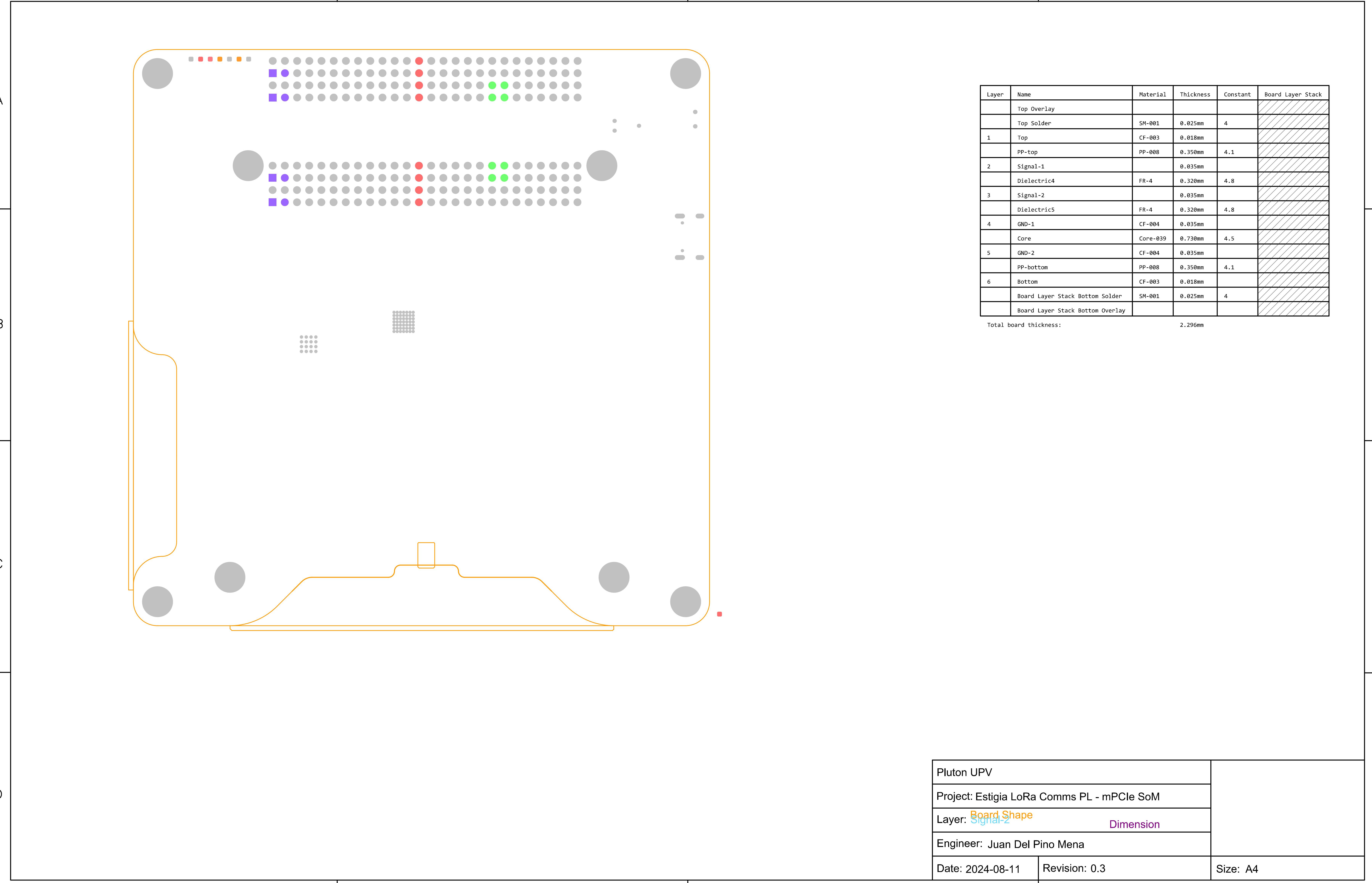


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top	CF-003	0.018mm		
2	PP-top	PP-008	0.350mm	4.1	
2	Signal-1		0.035mm		
3	Dielectric4	FR-4	0.320mm	4.8	
3	Signal-2		0.035mm		
4	Dielectric5	FR-4	0.320mm	4.8	
4	GND-1	CF-004	0.035mm		
5	Core	Core-039	0.730mm	4.5	
5	GND-2	CF-004	0.035mm		
6	PP-bottom	PP-008	0.350mm	4.1	
6	Bottom	CF-003	0.018mm		
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	
	Board Layer Stack Bottom Overlay				

Total board thickness: 2.296mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Board Shape Component Guard Dimension	
Component Guard	
Engineer: Juan Del Pino Mena	
Date: 2024-08-11	Revision: 0.3
Size: A4	



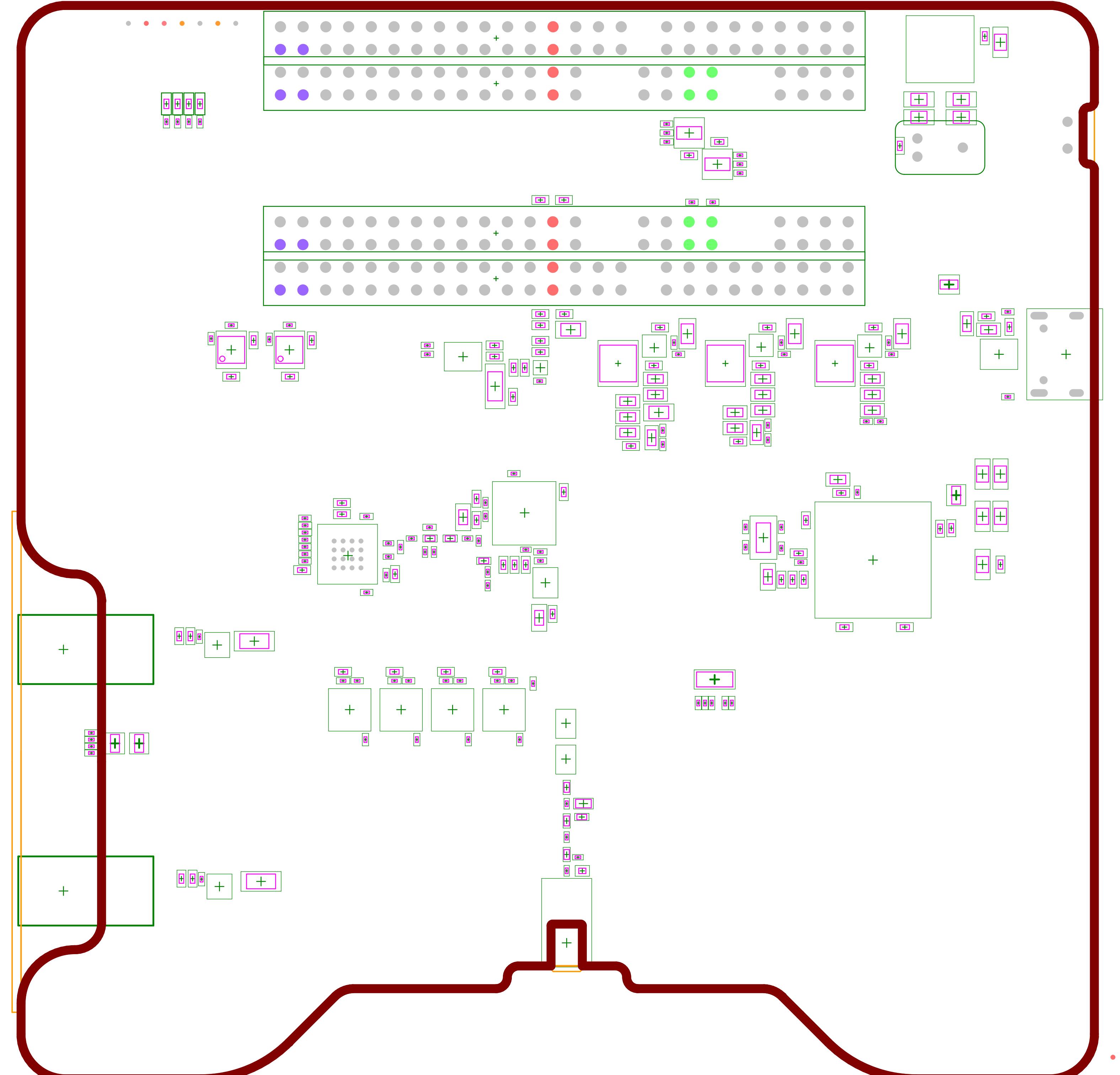


A

B

C

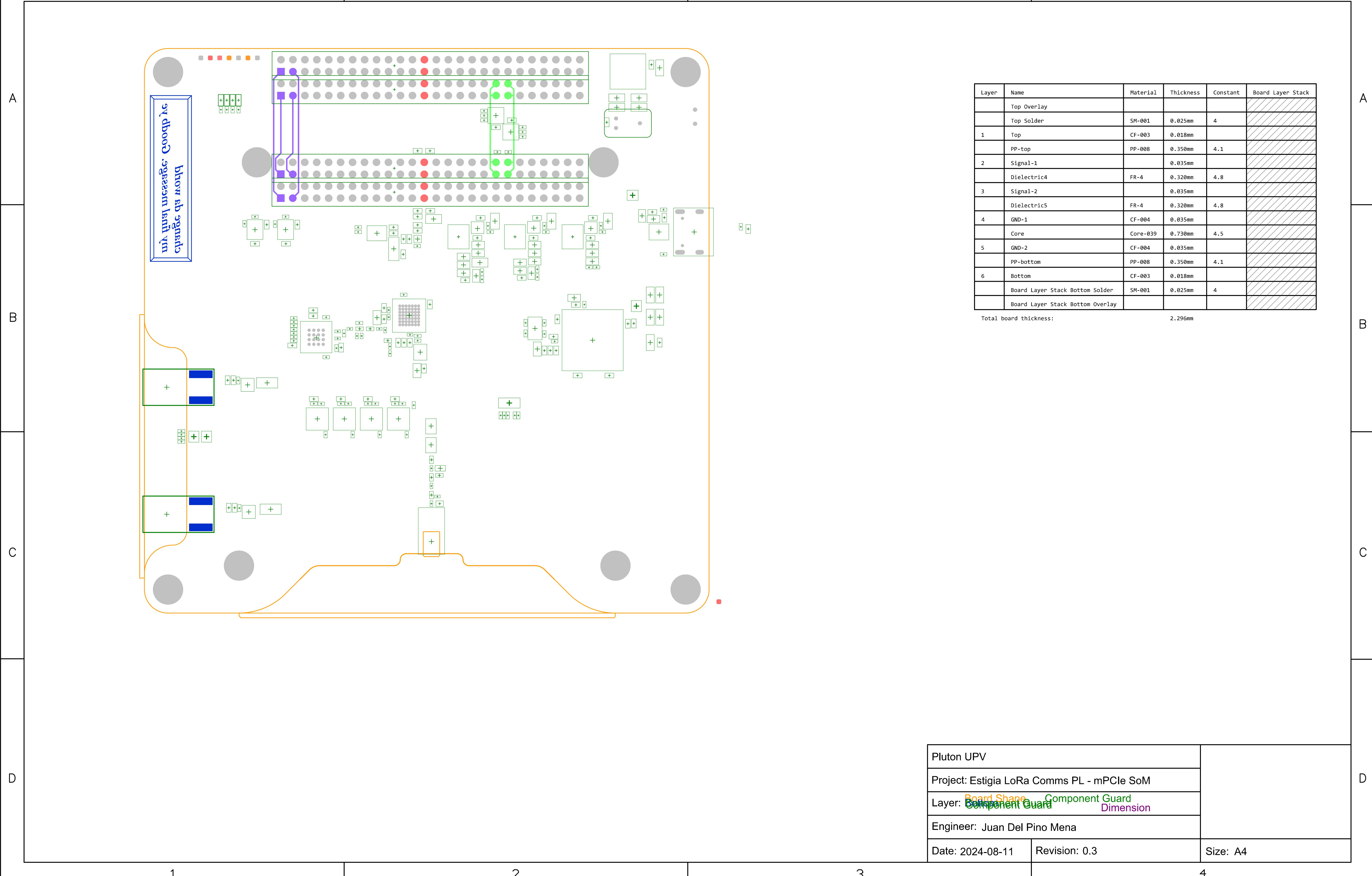
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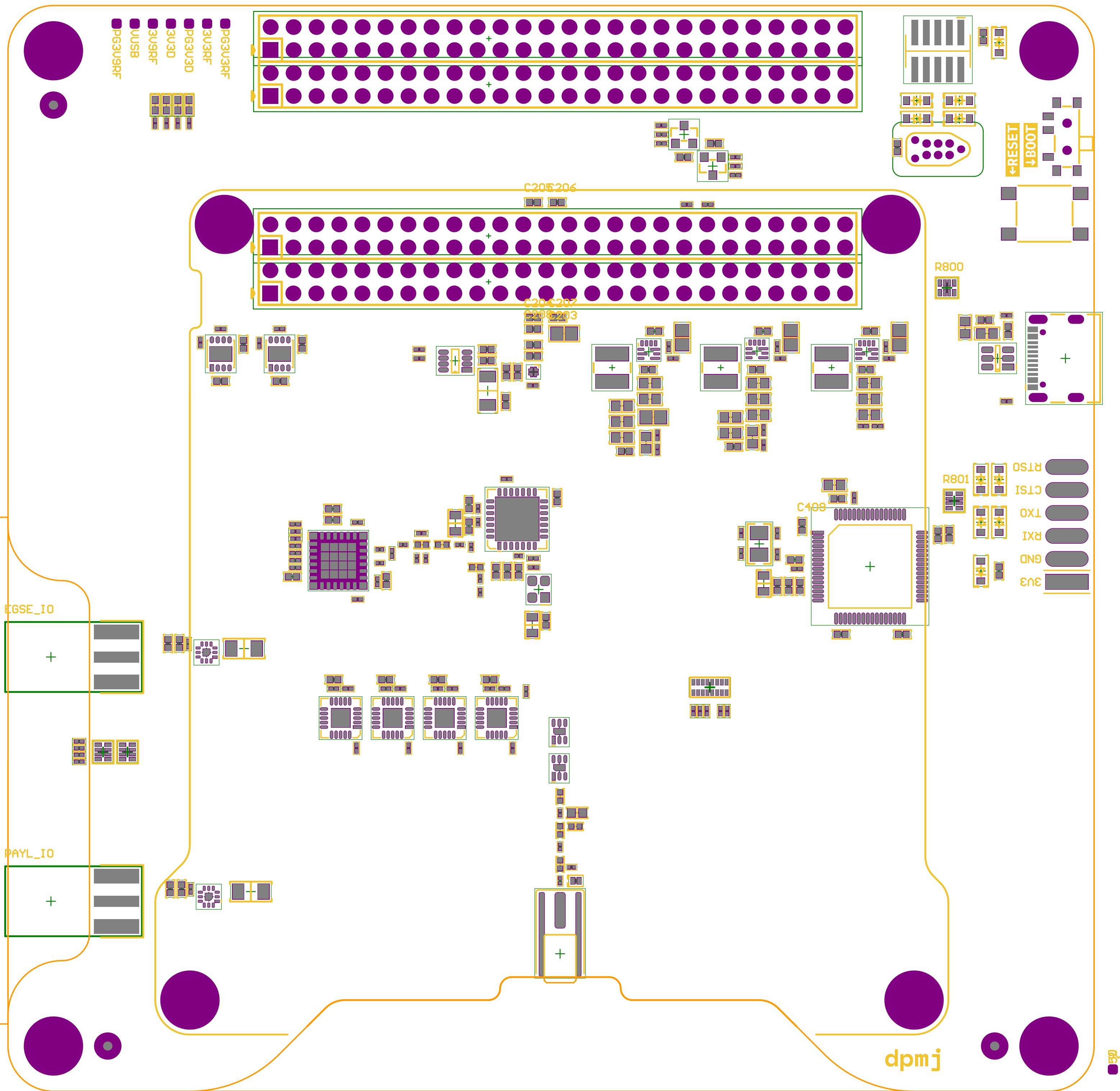


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top	CF-003	0.018mm		
2	PP-top	PP-008	0.350mm	4.1	
3	Signal-1		0.035mm		
	Dielectric4	FR-4	0.320mm	4.8	
4	Signal-2		0.035mm		
	Dielectric5	FR-4	0.320mm	4.8	
5	GND-1	CF-004	0.035mm		
	Core	Core-039	0.730mm	4.5	
6	GND-2	CF-004	0.035mm		
	PP-bottom	PP-008	0.350mm	4.1	
	Bottom	CF-003	0.018mm		
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	
	Board Layer Stack Bottom Overlay				

Total board thickness: 2.296mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Board Shape Component Guard	
Component Guard	Dimension
Engineer: Juan Del Pino Mena	
Date: 2024-08-11	Revision: 0.3
	Size: A4

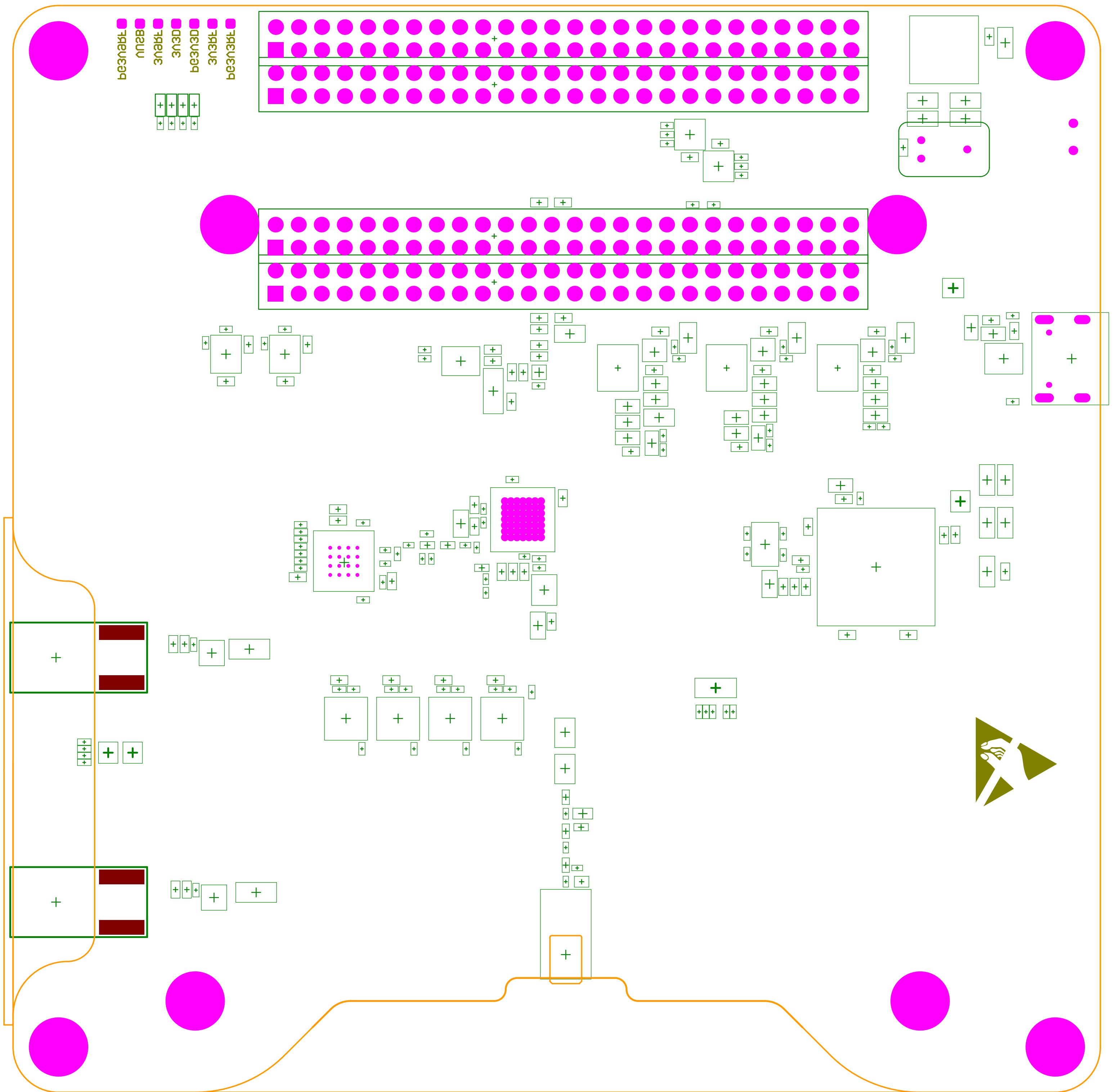




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top	CF-003	0.018mm		
2	Signal-1		0.035mm		
	Dielectric4	FR-4	0.320mm	4.8	
3	Signal-2		0.035mm		
	Dielectric5	FR-4	0.320mm	4.8	
4	GND-1	CF-004	0.035mm		
	Core	Core-039	0.730mm	4.5	
5	GND-2	CF-004	0.035mm		
	PP-bottom	PP-008	0.350mm	4.1	
6	Bottom	CF-003	0.018mm		
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	
	Board Layer Stack Bottom Overlay				

Total board thickness: 2.296mm

Pluto UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Board Shape Component Guard Compassion Guard Top Dimension	
Engineer: Juan Del Pino Mena	
Date: 2024-08-11	Revision: 0.3
	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top	CF-003	0.018mm		
2	PP-top	PP-008	0.350mm	4.1	
3	Signal-1		0.035mm		
	Dielectric4	FR-4	0.320mm	4.8	
3	Signal-2		0.035mm		
	Dielectric5	FR-4	0.320mm	4.8	
4	GND-1	CF-004	0.035mm		
	Core	Core-039	0.730mm	4.5	
5	GND-2	CF-004	0.035mm		
	PP-bottom	PP-008	0.350mm	4.1	
6	Bottom	CF-003	0.018mm		
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	
	Board Layer Stack Bottom Overlay				

Total board thickness: 2.296mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Bottom Paste Solder	Board Shape, Board Chipover, Solder Bottom Overlay
Engineer: Juan Del Pino Mena	Bottom Paste Solder, Board Layer Dimension Solder
Date: 2024-08-11	Revision: 0.3
	Size: A4

